

27. The device of claim 26 wherein a combined thickness of the oxide layer, the layer of undoped silicate glass, the layer of borophosphorous silicate glass, and the second layer of plasma-enhanced tetraethyl orthosilicate is less than approximately 15k angstroms.

REMARKS

Claims 1-4, 6-7, 9-10, 20, and 22-27 are currently pending. Claim 22 has been amended.

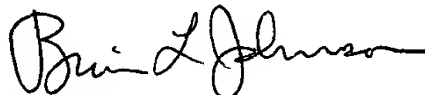
Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "**Version With Markings to Show Changes Made.**"

All of the claims remaining in the application are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

Claim 22 has been amended as follows:

22. (Amended) The device of claim ~~21~~20 wherein the layer of doped silicate glass is a layer of borophosphorous silicate glass.

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